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(12) **United States Design Patent**  
**Adams et al.**

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(54) **CONTACT FIELDS FOR A PRINTED CIRCUIT BOARD**

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(73) Assignee: **MODUS TEST AUTOMATION, LLC.**, Rockwall, TX (US)

(\*\*) Term: **14 Years**

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(51) **LOC (11) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/120, 121, 179, 182, 184, 199  
CPC ..... H05K 2201/10287; H05K 2201/10378;  
H05K 2201/10659; H05K 2201/10689;  
H05K 2201/10719; H05K 7/1084; H05K  
3/222; H05K 3/325; H05K 1/00; H05K  
1/0213; H05K 1/0215; H05K 1/182;  
Y10T 29/49147; Y10T 29/49149; Y10T  
29/49156

See application file for complete search history.

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(57) **CLAIM**

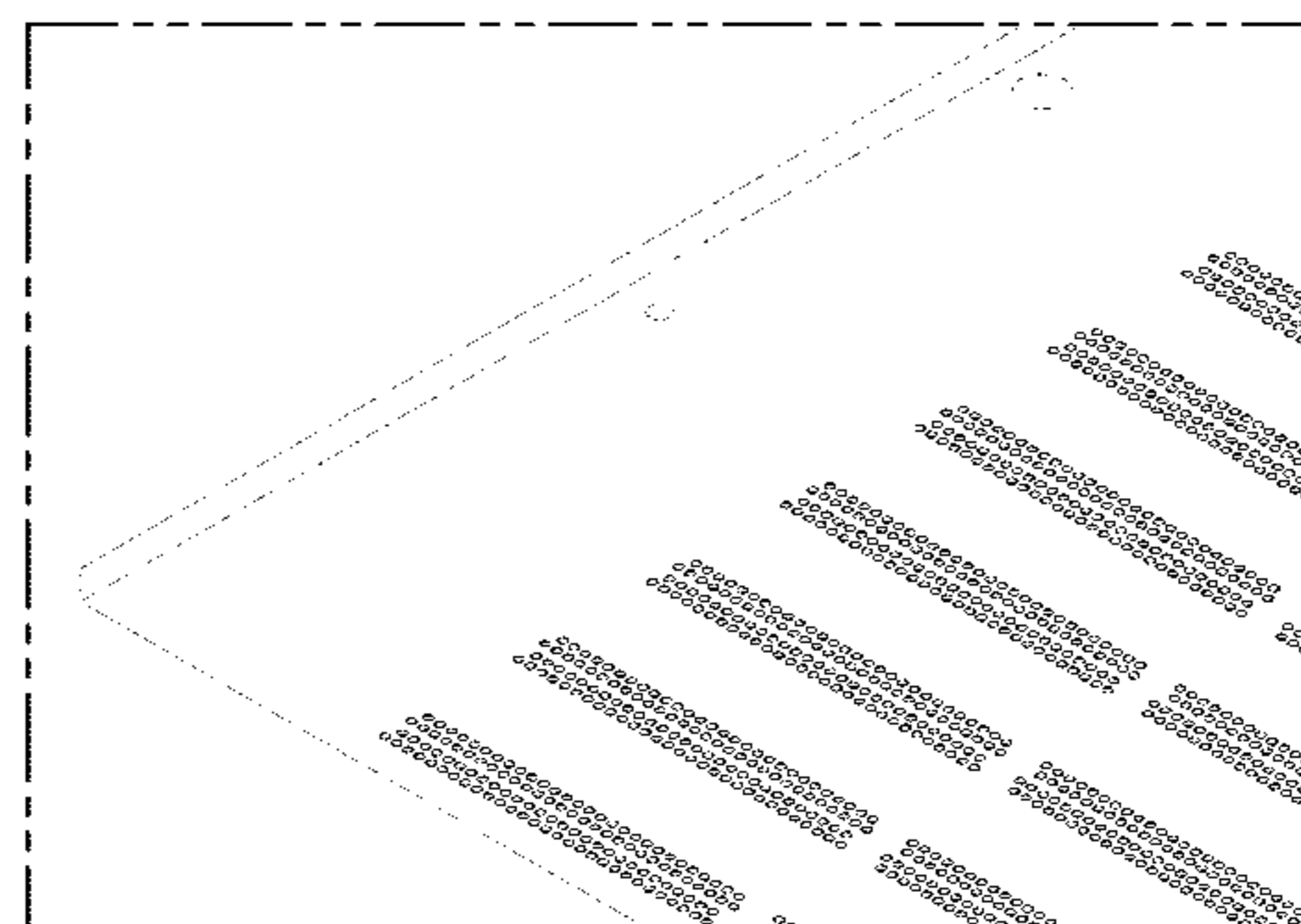
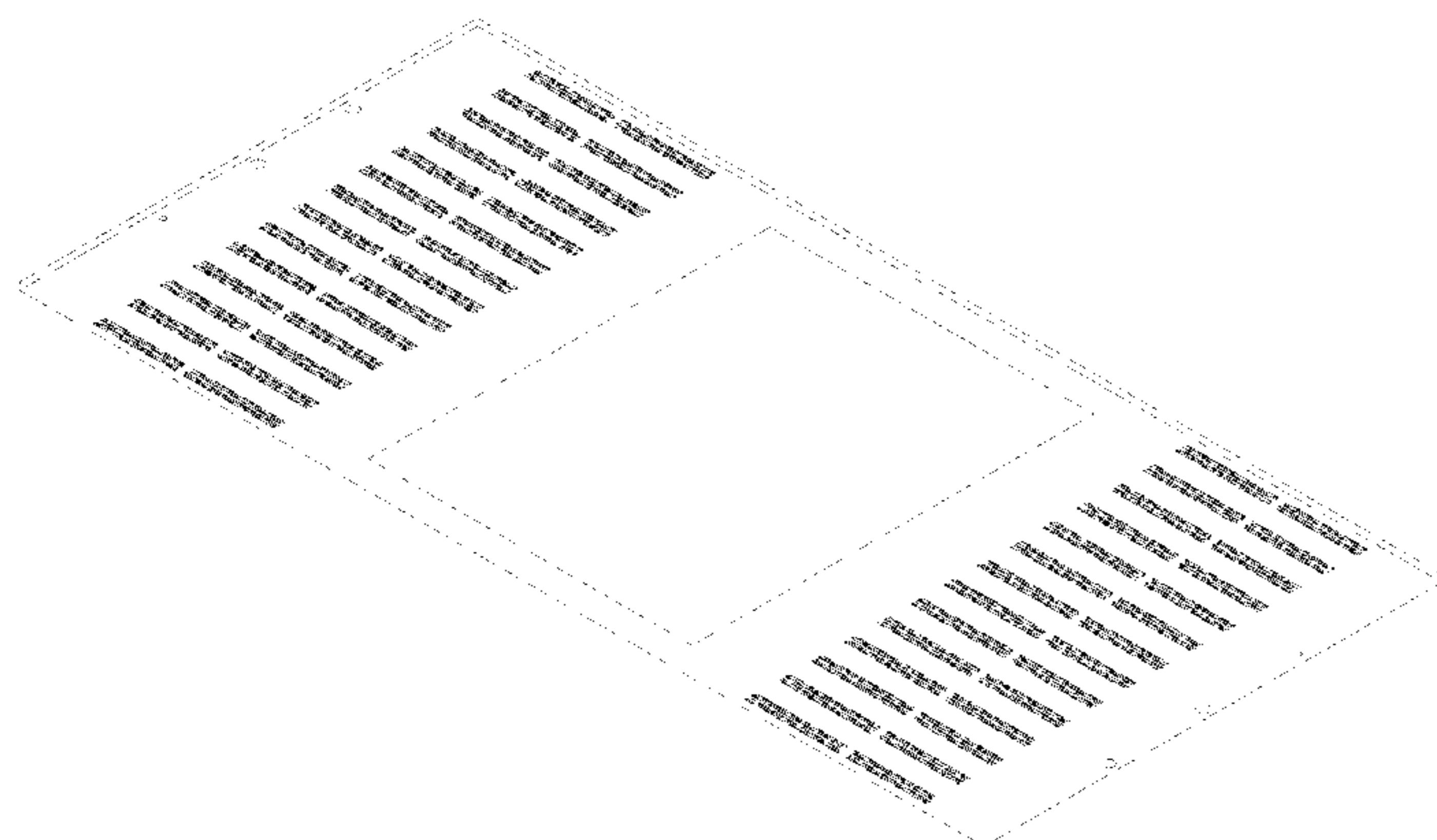
The ornamental design for a contact fields for a printed circuit board, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a top perspective view of a contact fields for a printed circuit board showing our new design;  
 FIG. 2 is a bottom perspective view thereof;  
 FIG. 3 is a right side elevation view thereof;  
 FIG. 4 is a left side elevation view thereof;  
 FIG. 5 is a front elevation view thereof;  
 FIG. 6 is a rear elevation view thereof;  
 FIG. 7 is a top plan view thereof;  
 FIG. 8 is a bottom plan view thereof;  
 FIG. 9 is a partial enlarged bottom perspective view thereof;  
 and,  
 FIG. 10 is a partial enlarged close-up bottom plan view thereof.

The broken lines shown represent portions of the contact fields for a printed circuit board that form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**



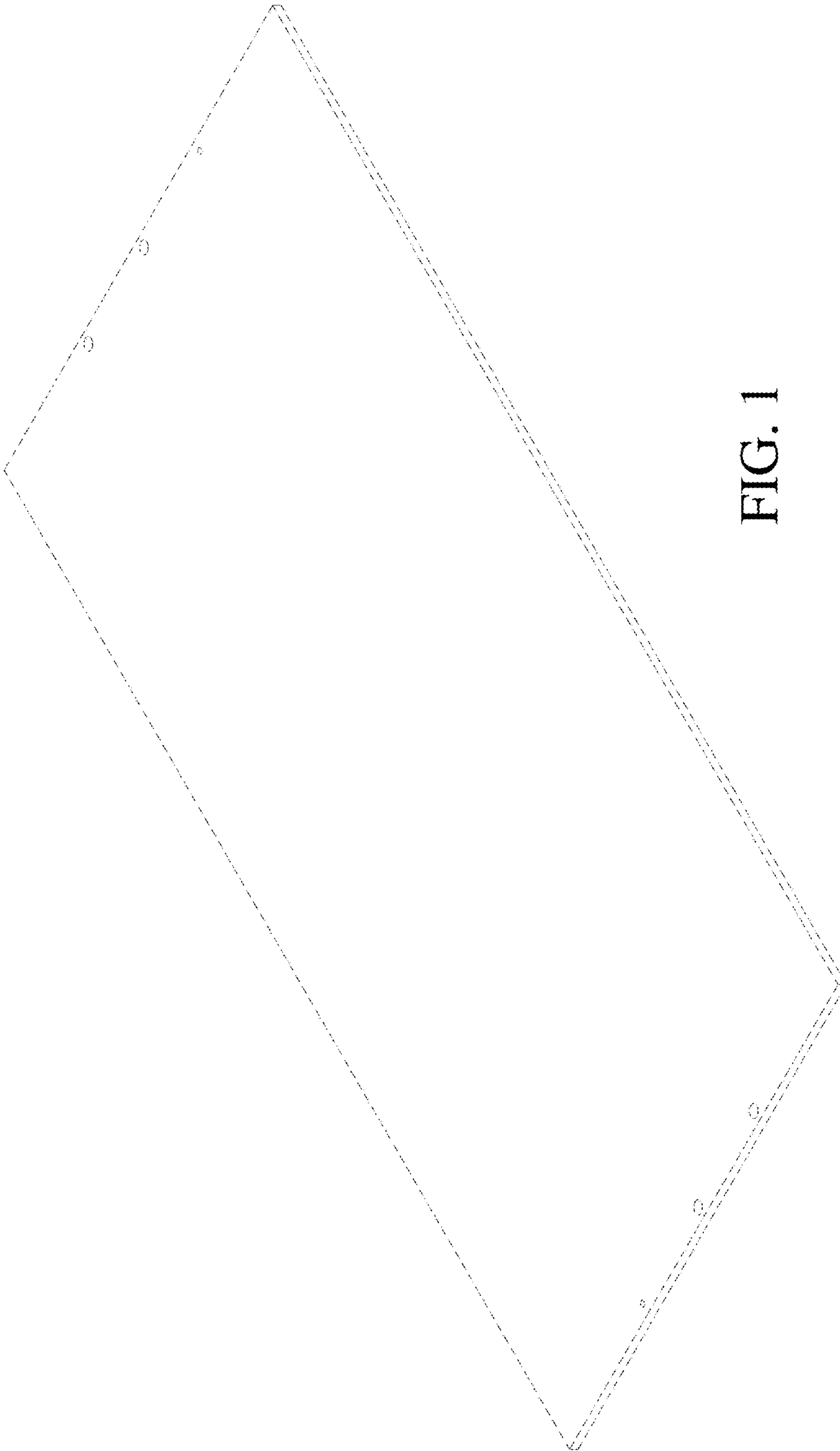


FIG. 1

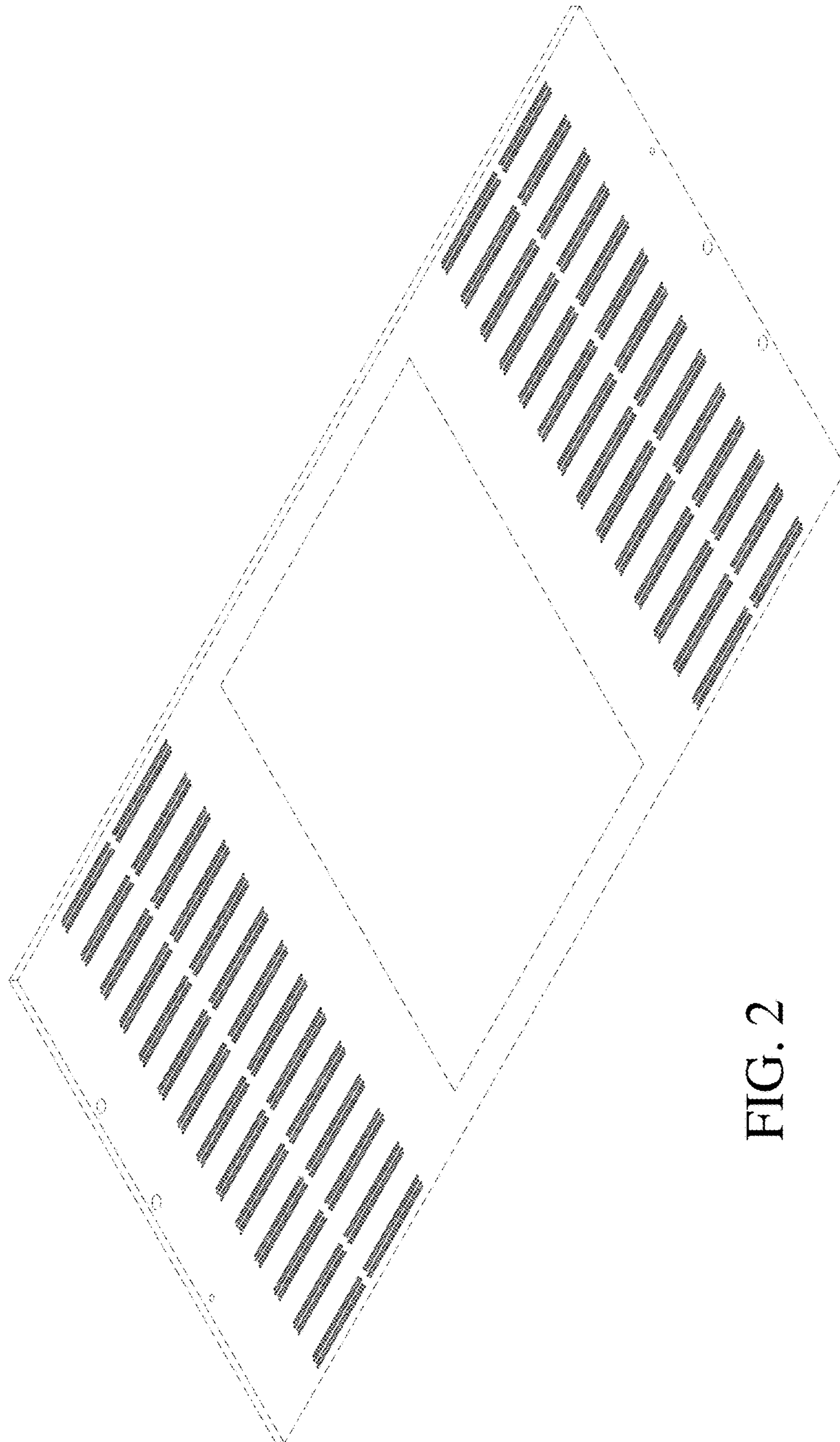


FIG. 2

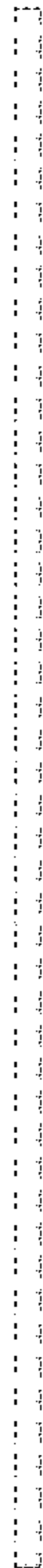


FIG. 3

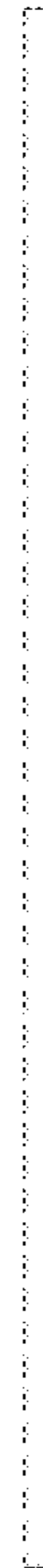


FIG. 4



FIG. 5



FIG. 6



FIG. 7

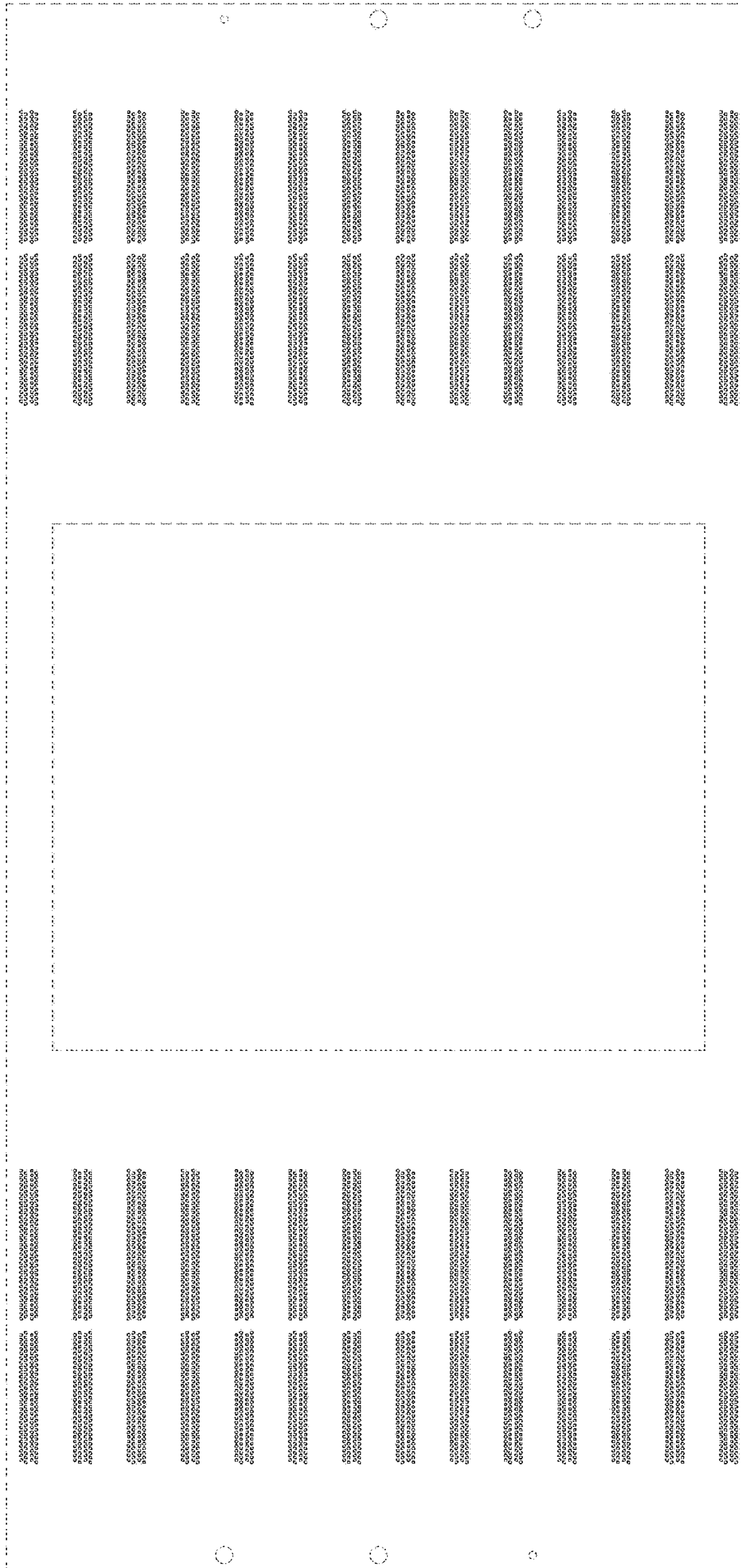


FIG. 8

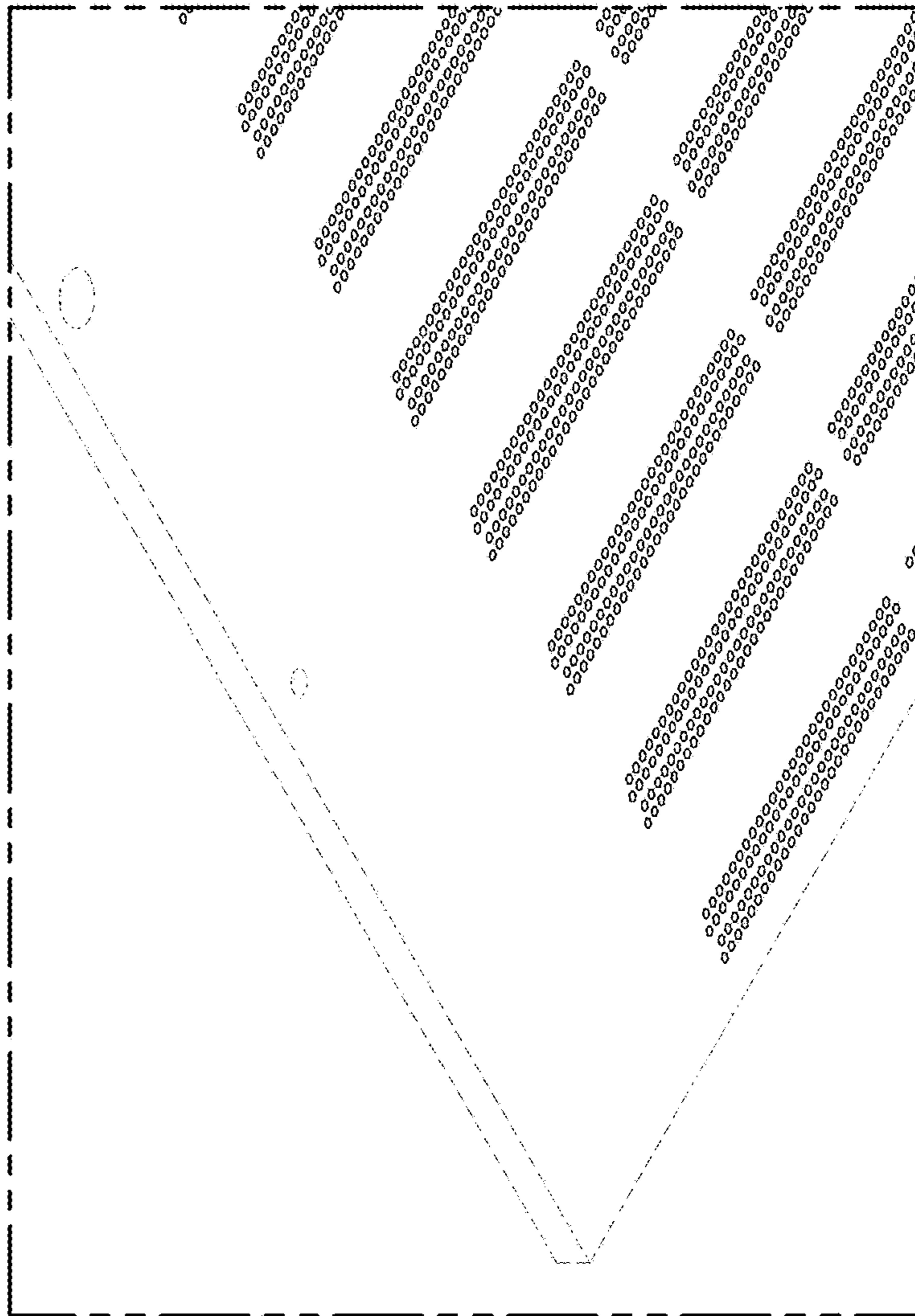


FIG. 9



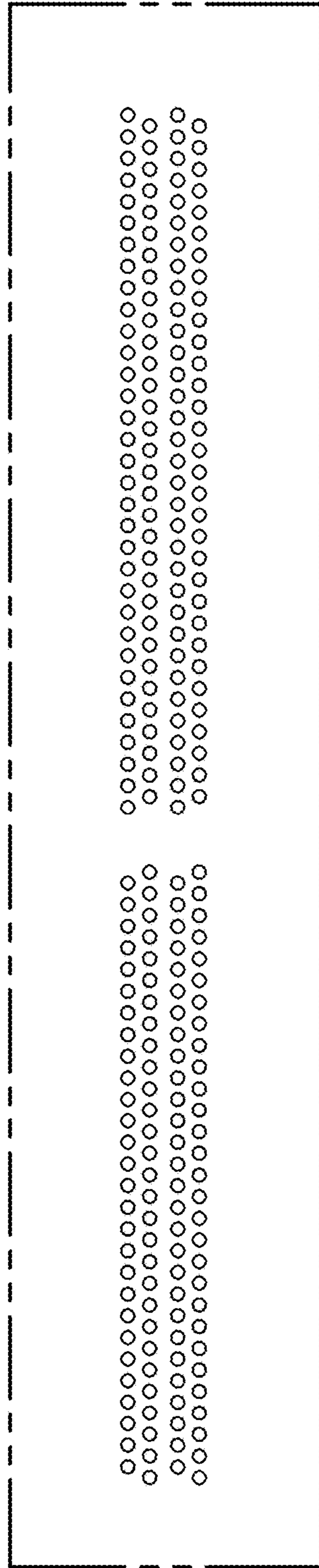


FIG. 10